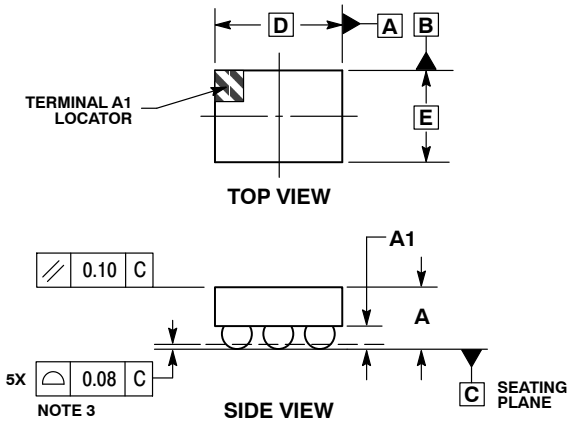
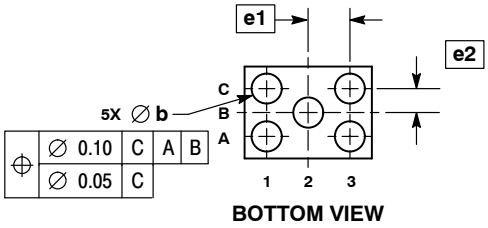
5 PIN FLIP−CHIP, 1.36x1.02
CASE 499BE−01
ISSUE A

DATE 06 OCT 2009

SCALE 4:1

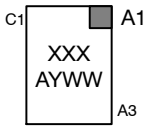




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.58	0.72
A1	0.21	0.29
b	0.26	0.37
D	1.31	1.41
E	0.97	1.07
e1	0.43 BSC	
e2	0.25 BSC	

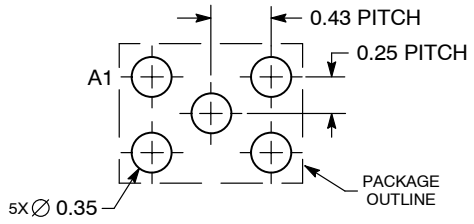
GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**5 PIN FLIP−CHIP, 1.36X1.02**	**PAGE 1 OF 1**